

Electronic Patent Application Fee Transmittal

Application Number:	10665309			
Filing Date:	22-Sep-2003			
Title of Invention:	Tungsten-copper interconnect and method for fabricating the same			
First Named Inventor:	Chen-Hua Yu			
Filer:	Daniel R. McClure/Hui Chin Barnhill			
Attorney Docket Number:	252011-1670			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Submission- Information Disclosure Stmt	1806	1	180	180
Total in USD (\$)				180